

Specification for Approval

Date: 2024/1/1

Customer:

BYTEK P/N: BCM4532F-02 SERIES

CUSTOMER P/N:

DESCRIPTION:

QUANTITY: pcs

REMARK:

Customer Approval Feedback

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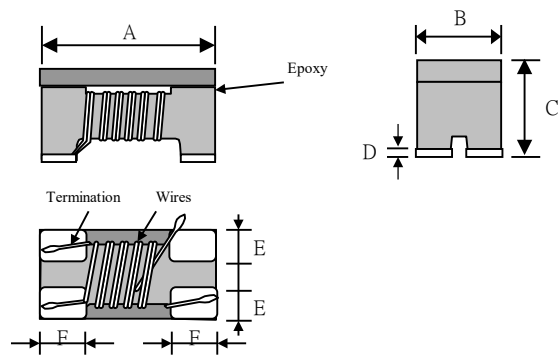
Sales Dep.

APPROVED	CHECKED
谢林阳	李昱珩

R&D Center

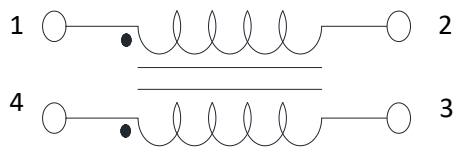
APPROVED	CHECKED	DRAWN
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一.外观图/DIMENSION (单位/UNIT: mm)



A	4.5±0.2
B	3.2±0.2
C	2.8±0.2
D	0.2±0.1
E	1.2 TYP
E	1.0 TYP

二.电路图/CIRCUIT DIAGRAM



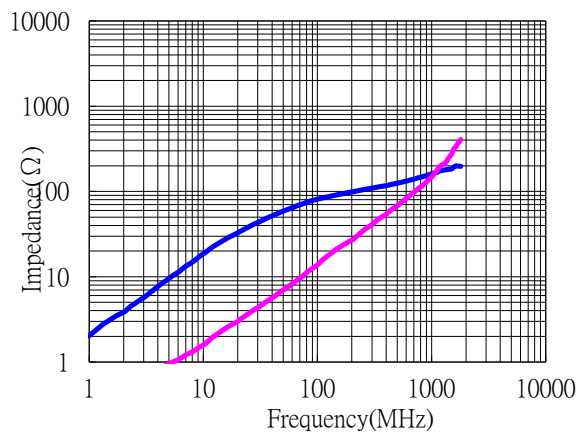
三.电气特性/ELECTRICAL CHARACTERISTIC

P/N	Z(Ω) 100MHz/0.5V Impedance ±25%	RDC (mΩ) Max	Rated Current (A) Max	IR (MΩ) Min	Rated Voltage (V) Max	Marking
BCM4532F-900S-02	90	50	4.0	10	50	N/A
BCM4532F-231S-02	230	50	3.5	10	50	N/A
BCM4532F-421S-02	420	55	3.2	10	50	N/A
BCM4532F-601S-02	600	60	2.5	10	50	N/A
BCM4532F-102S-02	1000	70	2.3	10	50	N/A
BCM4532F-282S-02	2800	350	0.9	10	50	N/A

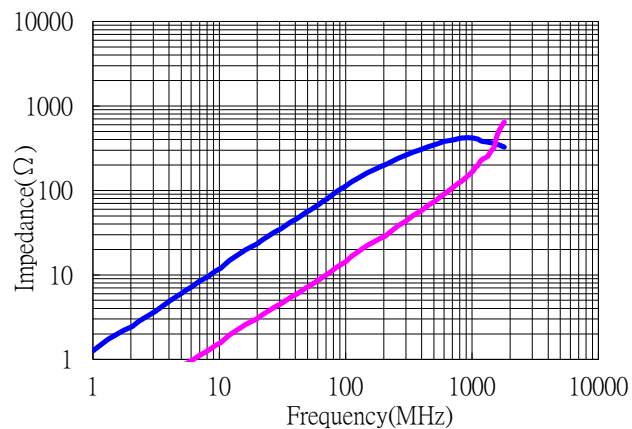
Operating temperature : -25 to +85℃
Storage temp. and humidity : -40 to +85℃ ,70%RH max
Typical Heat Rating DC Current would cause an approximately T of 40℃
If Use Wave soldering is there will be some risk. Re-flow soldering temperatures below 240 degrees, there will be unwitting risk

四. 曲线特性图表/ Graph characteristic chart

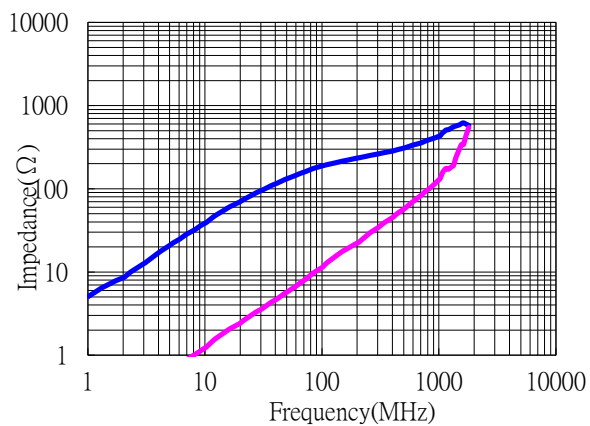
BCM4532F-900S-02



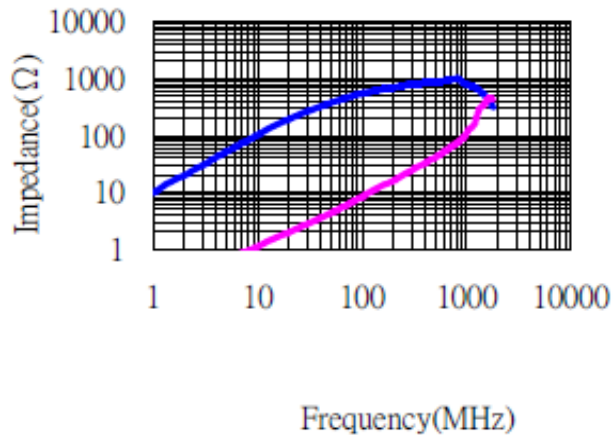
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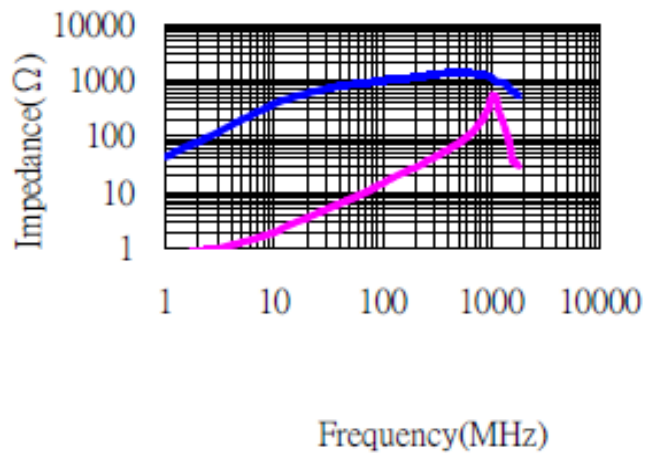
BCM4532F-421S-02



BCM4532F-601S-02



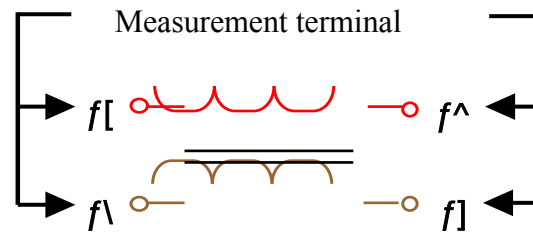
BCM4532F-102S-02



五. 测验设备/Test Equipment

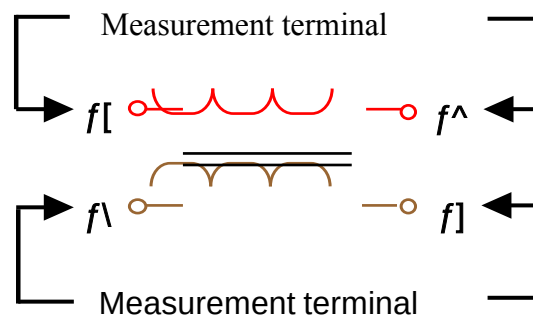
Impedance

Measured by using Agilent 4291A RF Impedance Analyzer.



DC Resistance

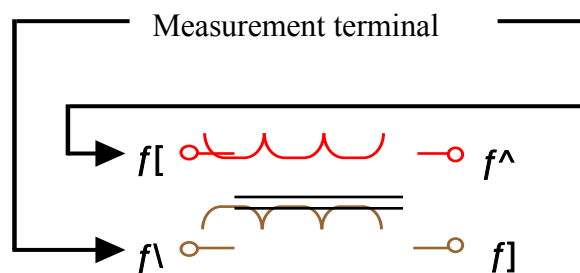
Measured by using Chroma 16502 mill ohm meter.



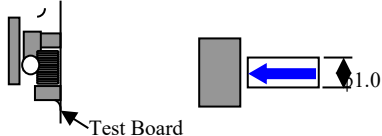
Insulation Resistance

Measured by using Chroma 19073

Measurement voltage : 50v ,Measurement time : 60 sec.

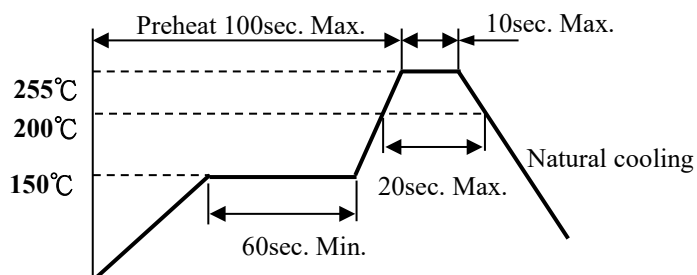


六.可靠性测试/RELIABILITY TESTING

TEST	Specification & Requirement		Method Used
Solderability	The surface of terminal/pin tested shall be covered with new solder by 90%		Solder heat proof: Preheating: $150 \pm 10^{\circ}\text{C}$ 60 seconds Soldering: $245 \pm 5^{\circ}\text{C}$ for 4 ± 1 sec
Solder Heat Resistance	Components should have not evidence of electrical and mechanical damage Impedance: within $\pm 15\%$ of initial value		Preheating: 150°C 60secs Solder temperature: $260 \pm 5^{\circ}\text{C}$ Flux: rosin Dip time: 10 ± 0.5 secs
Terminal strength	Series No.	F (Kg)	Solder a chip to test substrate and then laterally apply a force in the arrow direction 
	1608	0.5	
	2012	0.5	
	3216	1.0	
	3225	1.0	

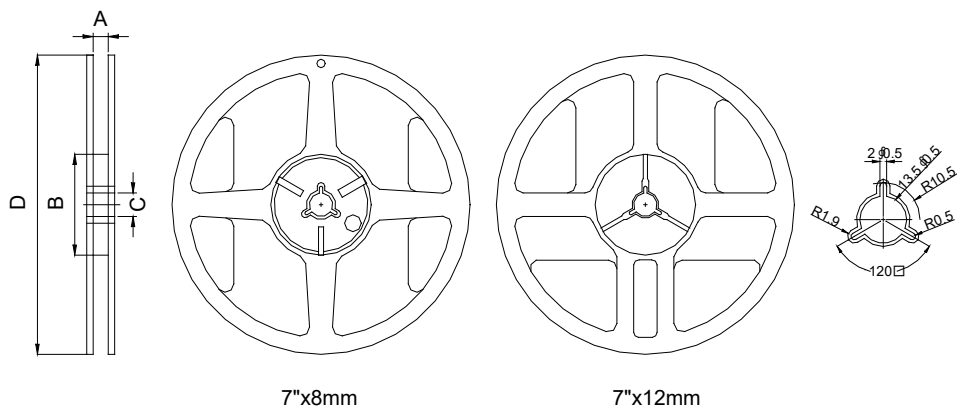
TEST	Specification & Requirement	Method Used
Thermal Shock	Impedance change within $\pm 15\%$ Without mechanical damage	-65°C , (30 mins) $\rightarrow$ room temp. (2 mins) $\rightarrow$ 125°C , (30 mins) $\rightarrow$ room temp. (2 mins) 50 cycles
Humidity Resistance	Impedance change within $\pm 15\%$ Without mechanical damage	Apply IDC current @ 60°C ambient Humidity: 90% Duration: 168 hrs
Low Temp. Storing	Impedance change within $\pm 15\%$ Without mechanical damage	Storing Temp. $-40 \pm 2^{\circ}\text{C}$ for total 168 $\pm 5/-0$ hours
High Temp. Storing	Impedance change within $\pm 15\%$ Without mechanical damage	Storing Temp. $125 \pm 2^{\circ}\text{C}$ for total 168 $\pm 5/-0$ hours

RECOMMENDED SOLDERING TEMP. GRAPH

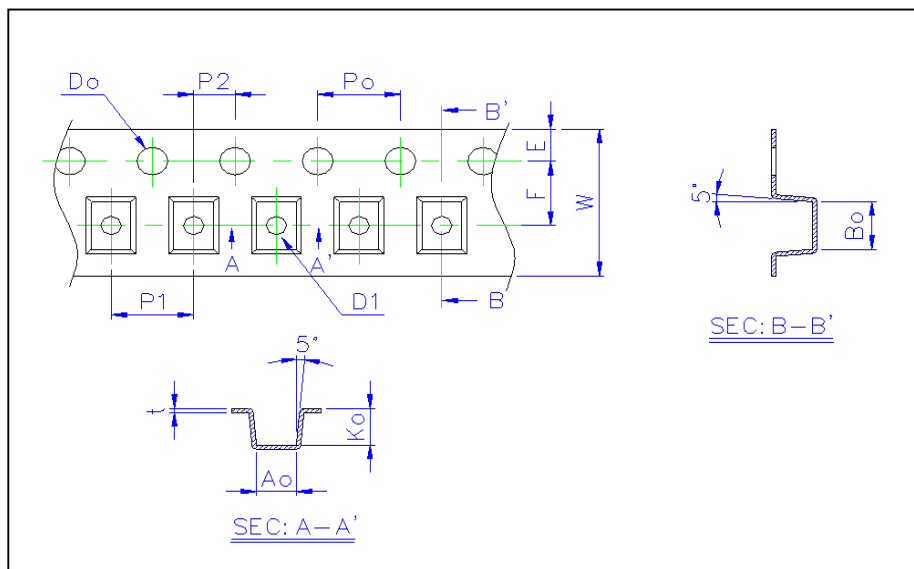


七.包装方式/PACKING LIST

Reel Dimension & Tape Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
7"x8mm	9.0±0.5	60±2	13.5±0.5	178±2
7"x12mm	13.5±0.5	60±2	13.5±0.5	178±2



Size	Ao(mm)	Bo(mm)	Ko(mm)	W(mm)	E(mm)	F(mm)	Po(mm)	P1(mm)	Do(mm)
1608	1.00±0.10	1.65±0.10	1.18±0.10	8.00±0.20	1.75±0.10	3.50±0.05	4.0±0.05	4.0±0.10	none
2012	1.50±0.10	2.35±0.10	1.45±0.10	8.00±0.20	1.75±0.10	3.50±0.05	4.0±0.05	4.0±0.10	1.0±0.1
3216	1.88±0.10	3.50±0.10	2.10±0.10	8.00±0.20	1.75±0.10	3.50±0.05	4.0±0.05	4.0±0.10	1.0±0.1
4532	4.90±0.10	3.45±0.10	3.05±0.10	12.00±0.20	1.75±0.10	5.50±0.05	4.0±0.05	8.0±0.10	1.5+0.1,-0

Packaging Quantity

Chip Size	1608	2012	3216	4532
8mm/ Reel	2000	2000	2000	
12mm/ Reel				500